

#### Description

The IRFH8324PbF uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> =120A

 $R_{DS(ON)} < 4.4 \text{m} U V_{GS} = 10 V$ 

### Application

Battery protection

Load switch

Uninterruptible power supply

### Package Marking and Ordering Information

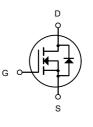
Product ID	Pack	Brand	Qty(PCS)
IRFH8324PbF	DFN5X6-8L	HXY MOSFET	5000

#### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units	
Vds	Drain-Source Voltage	30	V	
Vgs	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup> 120		
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup>	66	А	
Ідм	Pulsed Drain Current <sup>2</sup>	320	А	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	180	mJ	
las	Avalanche Current	Avalanche Current 60		
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	187	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
R <sub>0</sub> JA	Thermal Resistance Junction-Ambient <sup>1</sup> 62		°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	1.1	°C/W	





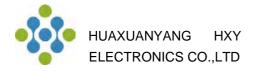


N-Channel MOSFET

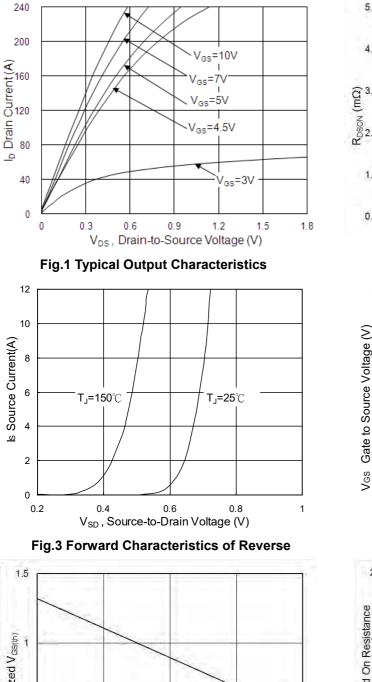


Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
₽BVbss/₽TJ	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I⊳=1mA		0.014		V/°C
		V <sub>GS</sub> =10V , I <sub>D</sub> =30A		3.5	4.4	
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		4.6	5.8	mΩ
VGS(th)	Gate Threshold Voltage		1.2		2.5	V
₽V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA		-4		mV/°C
		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
IDSS	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
lgss	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		50		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			56.9		
Qgs	Gate-Source Charge			13.8		nC
Qgd	Gate-Drain Charge			23.5		
Td(on)	Turn-On Delay Time			20.1		
Tr	Rise Time	V <sub>DD</sub> =15V , V <sub>GS</sub> =10V ,		6.3		
Td(off)	Turn-Off Delay Time	—R <sub>G</sub> =3.3 , I <sub>D</sub> =1A		124.6		ns
T <sub>f</sub>	Fall Time			15.8		
Ciss	Input Capacitance			4345		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		340		pF
Crss	Reverse Transfer Capacitance			225		
ls	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V$ , Force Current			85	A
Vsd	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , Is=1A , T <sub>J</sub> =25°C			1.2	V

# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)



## **Typical Characteristics**



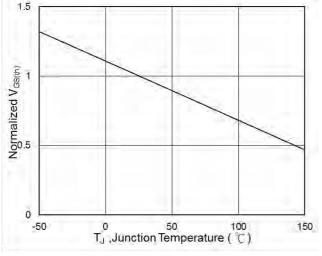


Fig.5 Normalized  $V_{GS(th)}$  v.s T<sub>J</sub>

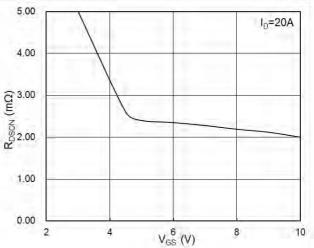
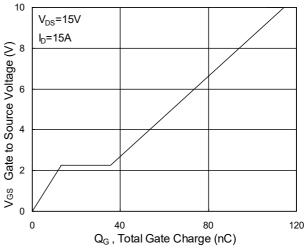


Fig.2 On-Resistance v.s Gate-Source



**Fig.4 Gate-Charge Characteristics** 

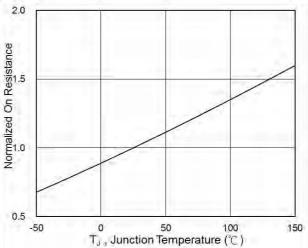


Fig.6 Normalized R<sub>DSON</sub> v.s T<sub>J</sub>



# IRFH8324PbF N-Channel Enhancement Mode MOSFET

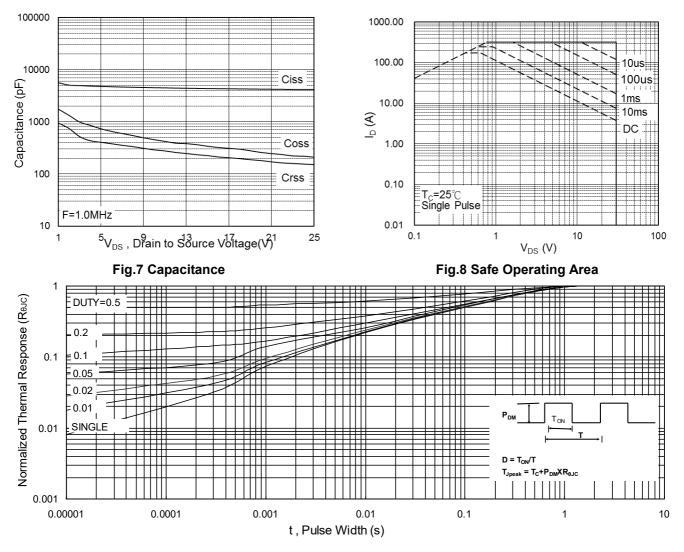


Fig.9 Normalized Maximum Transient Thermal Impedance

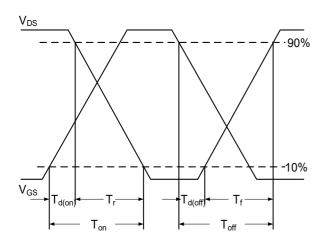
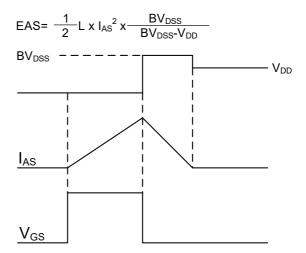
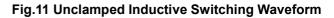


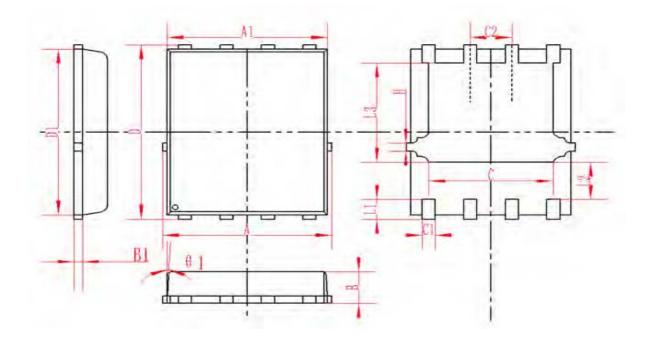
Fig.10 Switching Time Waveform







# **DFN5X6-8L Package Information**



SYMBOL	MM		INCH			
	MIN	NOM	MAX	MIN	NOM	MAX
А	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
В	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF		0.010REF			
С	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP		0.5TYP			
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
Н	0.24	0.25	0.26	0.009	0.010	0.010



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